

applying a top side dicing tape to the top surface;  
grinding the wafer at a bottom surface opposite the top  
surface and thereby laying open the trenches;  
applying a protective material on the bottom surface and at  
the same time filling all the trenches to protect the bottom  
surface and the bottom edges and corners; and  
hardening the protective material to form a protection layer.

Claim 3 (Twice Amended). A method of applying a protective  
coating to a bottom surface of a wafer, and of protecting  
bottom edges and corners of chips forming part of the wafer,  
which comprises the steps of:

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forming trenches in a top surface of the wafer;  
applying a top side dicing tape to the top surface;  
grinding the wafer at a bottom surface opposite the top  
surface and thereby laying open the trenches;  
applying a glue layer onto a mounting tape; and  
mounting the wafer on the mounting tape and at the same time  
causing the glue to fill all the trenches to protect the  
bottom surface and the bottom edges and corners.

Claim 5 (Amended). A method of applying a protective coating to a bottom surface of a wafer, which comprises the following steps:

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applying a protective foil onto a mounting tape; and  
mounting a bottom surface of the wafer onto the mounting tape with the protective foil facing and in contact with the bottom surface of the wafer to protect the bottom surface thereof.